

# 09N90W-VB Datasheet

## N-Channel 900V (D-S) Super Junction Power MOSFET

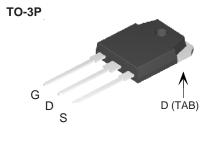
PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	900				
R <sub>DS(on)</sub> at 25 °C (Ω)	V <sub>GS</sub> = 10 V	0.75			
Q <sub>g</sub> max. (nC)	20				
Q <sub>gs</sub> (nC)	2.4				
Q <sub>gd</sub> (nC)	11				
Configuration	Single				

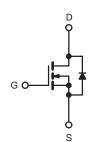
#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Qq)
- Avalanche energy rated (UIS)

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial





N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V <sub>DS</sub>	900		
Gate-Source Voltage			V <sub>GS</sub>	± 30	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I <sub>D</sub>	9		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		7.3	Α	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	28		
Linear Derating Factor				1.89	W/°C	
Single Pulse Avalanche Energy b			E <sub>AS</sub>	86	mJ	
Maximum Power Dissipation			P <sub>D</sub>	109	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C		dV/dt 50	1//20		
Reverse Diode dV/dt <sup>d</sup>			αν/αι	3.2	V/ns	
Soldering Recommendations (Peak Temperature) c	for 10 s			300	°C	

- a. Repetitive rating; pulse width limited by maximum junction temperature. b.  $V_{DD}=50$  V, starting  $T_J=25$  °C, L=28.2 mH,  $R_g=25$   $\Omega$ ,  $I_{AS}=3.5$  A.

- c. 1.6 mm from case. d.  $I_{SD} \le I_D$ , dl/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C.



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	72	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	0.7	C/VV	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		900	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.65	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		2	-	4	V
		$V_{GS} = \pm 20 \text{ V}$ $V_{GS} = \pm 30 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage	$I_{GSS}$			-	-	± 1	μΑ
		V <sub>DS</sub> = 900 V, V <sub>GS</sub> = 0 V		-	-	1	μА
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =620 V	V <sub>DS</sub> =620 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	10	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 6 A	-	0.75	-	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 6 A		-	19	-	S
Dynamic		•					
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1  MHz		-	373	-	pF
Output Capacitance	C <sub>oss</sub>			-	26	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	14	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 520 V, V <sub>GS</sub> = 0 V		-	46	-	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	64	-	
Total Gate Charge	Qg			-	26		
Gate-Source Charge	$Q_{gs}$	$V_{GS} = 10 \text{ V}$ $I_D = 6 \text{ A}, V_{DS} = 520 \text{ V}$		-	2.1	-	nC
Gate-Drain Charge	$Q_{gd}$			-	2.8	-	<u>l</u>
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD} = 620 \text{ V}, I_D = 6 \text{ A},$ $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		-	26	-	ns
Rise Time	t <sub>r</sub>			-	55.7	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	71	-	
Fall Time	t <sub>f</sub>			-	41	-	
Gate Input Resistance	$R_{g}$	f = 1 MHz, open drain		-	3.5	-	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	18	- A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 6 A, V <sub>GS</sub> = 0 V		-	-	1.4	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 6 A, dI/dt = 100 A/µs, V <sub>R</sub> = 400 V		-	192	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	2.4	-	μC
Reverse Recovery Current	I <sub>RRM</sub>			<u> </u>	11	<del>                                     </del>	A

## Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

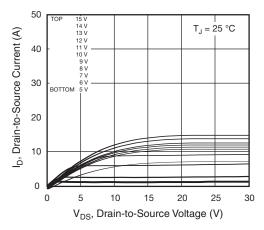


Fig. 1 - Typical Output Characteristics

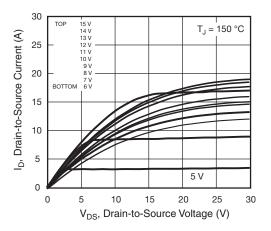


Fig. 2 - Typical Output Characteristics

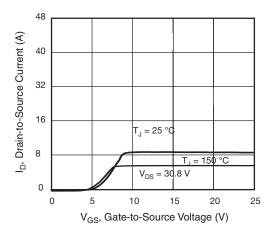


Fig. 3 - Typical Transfer Characteristics

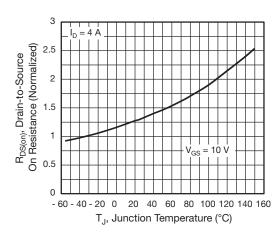


Fig. 4 - Normalized On-Resistance vs. Temperature

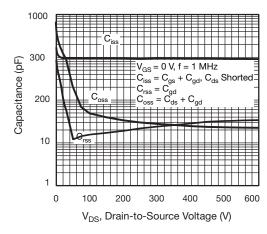


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

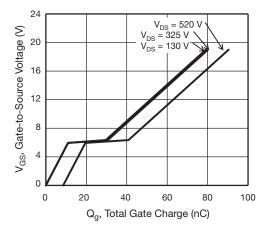


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



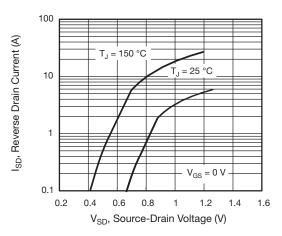


Fig. 7 - Typical Source-Drain Diode Forward Voltage

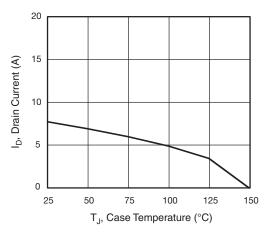


Fig. 9 - Maximum Drain Current vs. Case Temperature

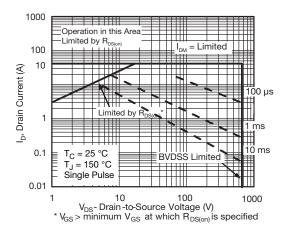


Fig. 8 - Maximum Safe Operating Area

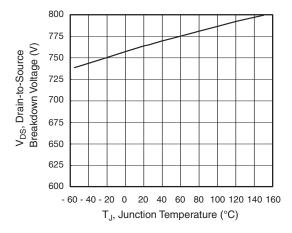


Fig. 10 - Temperature vs. Drain-to-Source Voltage

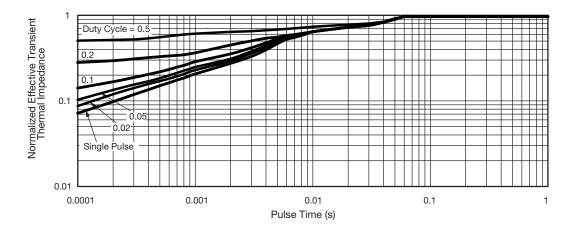


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

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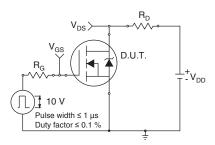


Fig. 12 - Switching Time Test Circuit

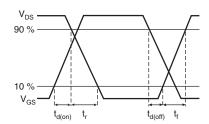


Fig. 13 - Switching Time Waveforms

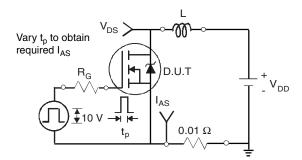


Fig. 14 - Unclamped Inductive Test Circuit

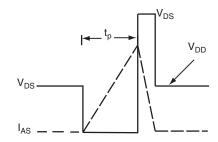


Fig. 15 - Unclamped Inductive Waveforms

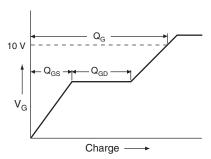


Fig. 16 - Basic Gate Charge Waveform

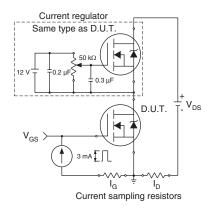
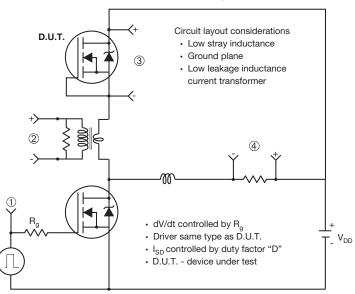


Fig. 17 - Gate Charge Test Circuit

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### Peak Diode Recovery dV/dt Test Circuit



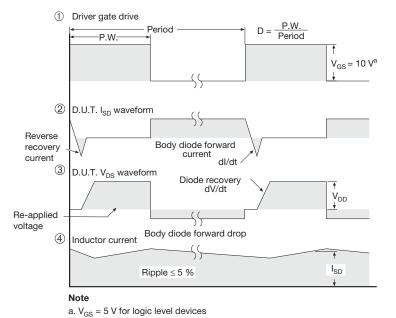


Fig. 18 - For N-Channel



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